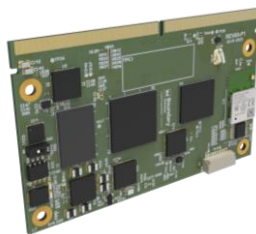


SECURE, SMART, STANDARDIZED, AND CONNECTED IOT: POWERFUL NXP EDGE PROCESSING WITH WI-FI 5 AND BLUETOOTH 5.2

Featuring **NXP i.MX 8M Plus**
and Sterling-LWB5+ (**Infineon CYW4373E**)

Up to **1.8 GHz quad-core Cortex-A53**
and **800 MHz Cortex-M7**

Wi-Fi 5 (**802.11ac**) and **Bluetooth 5.2**



Our customers asked for a high performance, robust SoM that simplifies their BOM, has reliable connectivity, uses a standard form factor, and is globally certified. One with multiple software options, a proven security architecture, long term software support, and security fixes.

Our new Nitrogen8M Plus SMARC is powered by **NXP's innovative i.MX 8M Plus** processor, **NXP PMIC PCA9450**, and our Sterling LWB5+ Wi-Fi 5 / Bluetooth 5.2 radio based on **Infineon's CYW4373E**, high performance LPDDR4 RAM, and eMMC storage. We combine this with our common SMARC carrier board; together they serve as a single board computer (SBC) that can speed your product to market. Alternately, work with us to create a custom carrier that fits your mechanical, environmental, temperature, and interface requirements.

- **Powerful Heterogenous Multiprocessing:** Up to 1.8 GHz quad-core Cortex-A53 microprocessor and 800 MHz Cortex-M7 microcontroller allow you to run Linux and an RTOS on dedicated, hardware-firewalled subsystems.
- **Dedicated Machine Learning:** High-performance edge machine learning via an integrated neural processing unit, delivering up to 2.3 TOPS.
- **Diversity of Interfaces:** Multiple display, network, data, audio and camera interfaces.
- **SMARC 2.1 Standard Form Factor: 82mm x 50mm** SMARC edge connector form factor which includes **onboard ethernet PHYs and a USB hub controller**. One design supports multiple processor, memory, and wireless configurations.
- **Hardware Upgrade Roadmap:** Build a product design that can easily be upgraded to the latest processors and wireless options as future Laird Connectivity SOMs based on the SMARC standard are released.
- **Advanced Common Carrier/Development Board:** Display, camera, audio, Ethernet, USB, PCI-Express, CAN, I2C, SPI, UART, and more. Use in development, as an SBC equivalent in a product, or as reference designs for your carrier board design.

- **Wi-Fi 5 (802.11ac) and Bluetooth 5.2 Classic & Low Energy (LE)**
- **Operating Temperature Range**
 - Commercial Rating (0° to +70 °C)
 - Industrial Rating (-40° to +85 °C)
- **Multiple high performance memory options:**

2GB LPDDR4 /	4GB LPDDR4 /	8GB LPDDR4 /
16GB eMMC	16GB eMMC	16GB eMMC (MOQ required)
- Extensive range of **pre-certified antennas** for Sterling-LWB5+
- **US based manufacturing with Global Options:** Manufacture in USA for local customer base and US market needs. Global manufacturing capability as part of Laird Connectivity footprint, growing reach to EMEA & APAC regions
- **Diverse Software and Board Support Options:** Choose from Yocto Linux/Android/Ubuntu for Cortex-A53s, Zephyr RTOS/FreeRTOS for the Cortex-M7
- **Secure and Encrypted Boot, Secure Enclave, and Secure File Storage:** Robust, secure, and optionally encrypted boot mechanism to ensure only trusted software boots on your device. Optionally store and use secure keys, certificates, and credentials in run-time isolated trusted environment.
- **Power Efficient:** NXP PMIC, power optimized LPDDR4 and eMMC memory, core shut off, clock/voltage scaling, low power interfaces, power optimized single stream Wi-Fi mode enable highly optimized power consumption
- **Long term hardware availability and software support:** Laird Connectivity's products are specifically designed to meet the needs of the industrial and medical markets, which typically require 10 year or more product lifecycles. **Long-term software support** includes LTS Yocto Linux and Zephyr RTOS support with vulnerability remediation.

FEATURES AT A GLANCE



RELIABLE CONNECTIVITY: WI-FI 5 AND BT 5.2

Excellent Wi-Fi and BT Classic / LE connectivity in difficult environments, plus enterprise Wi-Fi support via WPA3-Enterprise for more secure and robust connections.



ML, GRAPHICS, VIDEO, VISION, AND AUDIO - UP TO 3 DISPLAYS

2.3 TOPS Machine Learning/Neural Processing Unit, up to 1200p60 or 4Kp30 displays, 2 shader GPU, 1080p60 multi codec encode and decode VPU, 2 MIPI-CSI camera interfaces, dedicated Image Signal Processing up to 12 MP, HiFi4 audio DSP



SECURE ENCLAVE AND SECURE BOOT POWERED BY I.MX 8M PLUS

Dedicated on-board security hardware, secure boot Linux, and high-performance and flexible secure storage system for passwords, certificates, and data storage.



ROBUST SOFTWARE AND SPEED TO MARKET

Choose from Yocto Linux, Android, and Ubuntu for the Cortex-A53s, Zephyr RTOS and FreeRTOS for the Cortex-M7



GLOBAL RADIO APPROVALS

Carries several modular FCC, IC, CE, UKCA, RCM, MIC, KC and Bluetooth SIG approvals.



PERSONAL SUPPORT FROM DESIGN TO MANUFACTURE

Our industry-renowned support and field application engineering team is passionate about helping you speed your design to market.

APPLICATION AREAS



Smart Buildings and Appliances



Touchscreens and Displays



Industrial IoT, Vision Systems



Food and Beverage



Medical Devices

KEY SPECIFICATIONS

CATEGORY	FEATURE	SPECIFICATION				
Processors	Microprocessor	4x Cortex®-A53 cores @ up to 1.8 GHz				
	Microcontroller	1x Cortex®-M7 core @ 800 MHz				
	Audio	Tensilica® HiFi 4 DSP				
	Graphics	GC7000UL with 2 shaders for 3D and GC520L for 2D				
	Machine Learning	Neural Processing Unit (NPU) with 2.3 TOP/s				
Memory	RAM	2GB and 4GB. 8GB with qualifying MOQ. <i>(For custom sizes, please contact Sales)</i>				
	Storage	16GB. <i>(For custom sizes, please contact Sales)</i>				
Machine Learning	Neural Processing Unit	<ul style="list-style-type: none"> Keyword detect, noise reduction, beamforming Image recognition (i.e. ResNet-50) Speech recognition (i.e. Deep Speech 2) 				
Graphics and Video	Graphics Processing Unit	<ul style="list-style-type: none"> 166 million triangles/sec 16 GFLOPs 32-bit 2D acceleration 1.0 giga pixel/sec OpenGL ES 1.1, 2.0, 3.0, OpenCL 1.2, Vulkan 				
	Video Processing Unit	<table border="0"> <tr> <td>Video Decode</td> <td>Video Encode</td> </tr> <tr> <td> <ul style="list-style-type: none"> 1080p60 HEVC/H.265 Main, Main 10 (up to level 5.1) 1080p60 VP9 Profile 0, 2 1080p60 VP8 1080p60 AVC/H.264 Baseline, Main, High decoder </td> <td> <ul style="list-style-type: none"> 1080p60 AVC/H.264 encoder 1080p60 HEVC/H.265 encoder </td> </tr> </table>	Video Decode	Video Encode	<ul style="list-style-type: none"> 1080p60 HEVC/H.265 Main, Main 10 (up to level 5.1) 1080p60 VP9 Profile 0, 2 1080p60 VP8 1080p60 AVC/H.264 Baseline, Main, High decoder 	<ul style="list-style-type: none"> 1080p60 AVC/H.264 encoder 1080p60 HEVC/H.265 encoder
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Display Interfaces	<ul style="list-style-type: none"> 1x MIPI DSI, up to UWHD and WUXGA 1x LVDS Tx, up to 1920x1080p60 1x HDMI 2.0a Tx, up to 4kp30 					
Vision	Camera	<ul style="list-style-type: none"> 1x 4-lane MIPI CSI 1x 2-lane MIPI CSI 				
	Image Signal Processor	375 Mpixel/s HDR ISP supporting configurations, such as 12MP@30fps, 4kp45, or 2x 1080p80				
Audio	Audio Interfaces	<ul style="list-style-type: none"> 2x I2S (Optionally 1 as HDA) ASRC eARC/ARC (HDMI) 				
Peripherals	Input/Output	<ul style="list-style-type: none"> 1x PCIe Gen3 1-Lane Dual Mode with PHY 3x UART 5 Mbit/s 2x USB 3.0/2.0 with PHY 3x I2C 2x USB 2.0 with PHY 2x SPI 2x Gbit Ethernet with IEEE® 1588, AVB (One also supports TSN) 1x SDIO 3.0/eMMC 5.1 2x CAN (Optionally CAN-FD on I-Temp) 12x GPIO 				
Wireless Specification	Wi-Fi	Wi-Fi 5 (802.11ac)				
	Frequency	Dual-Band 2.4GHz & 5GHz				
	Bluetooth	Bluetooth 5.2				
	Transmit Power	+ 18 dBm (maximum)				
	Antenna Options	MHF4 connector for external antenna				
Key Wi-Fi Features	Raw Data Rates (Air)	Wi-Fi 5 433.3Mbit/s - MCS9, 80MHz, 256QAM, SGI				
Key Bluetooth Features	Wi-Fi 5 (802.11ac)	<ul style="list-style-type: none"> IEEE 802.11 a/b/g/n/ac OFDM 20, 40 & 80MHz bandwidth support 				
	Bluetooth V	<ul style="list-style-type: none"> Classic Bluetooth – BR / EDR Up to 7 Bluetooth LE connections Central / Peripheral Modes LE Secure Connections 				
Supply Voltage		5 V				
Physical	Dimensions	SMARC 2.1 Standard - 82mm x 50mm				
Environmental	Temp Range	0°C to +70°C (Commercial) and -40° to +85 °C (Industrial)				
Miscellaneous	Lead Free	Lead-free and RoHS-compliant				
	Carrier Board	Carrier board, accessories, and evaluation software				
Qualifications	Bluetooth® SIG	Bluetooth SIG Qualified Listing				
Regulatory	Approvals	FCC/IC/CE/MIC/RCM				

For full specifications on the Nitrogen8M Plus SMARC, please see the appropriate datasheet.

Part #	Description
N8MP_SMARC_SOM_2r16eWB	SMARC SOM: i.MX8M Quad Plus / 2GB / 16GB eMMC / LWB5+
N8MP_SMARC_SOM_4r16eWB	SMARC SOM: i.MX8M Quad Plus / 4GB / 16GB eMMC / LWB5+
N8MP_SMARC_SOM_2r16eWB_i	SMARC SOM: i.MX8M Quad Plus / 2GB / 16GB eMMC / LWB5+ / Industrial Temp
N8MP_SMARC_SOM_4r16eWB_i	SMARC SOM: i.MX8M Quad Plus / 4GB / 16GB eMMC / LWB5+ / Industrial Temp
N8MP_SMARC_SOM_8r16eWB	SMARC SOM: i.MX8M Quad Plus / 8GB / 16GB eMMC / LWB5+ (MOQ requirements)
SMARC_CAR_BRD	Universal Carrier Board - SMARC (Note - SOM sold separately)

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